



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN# 20190823000.1**

**Qualification of DMOS6 as an additional Fab site option for select devices and  
Datasheet Update  
Change Notification / Sample Request**

**Date:** August 30, 2019  
**To:** Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)). For sample requests or sample related questions, contact your local Field Sales Representative.

PCN Team  
SC Business Services


**20190823000.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
BQ25970YFFT	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20190823000.1		<b>PCN Date:</b>	Aug 30, 2019	
<b>Title:</b>	Qualification of DMOS6 as an additional Fab site option for select devices and Datasheet Update				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>		<b>Dept:</b>	Quality Services	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Nov 30, 2019		<b>Estimated Sample Availability:</b>	Date provided at sample request.	
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input checked="" type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
	<input type="checkbox"/>	Part number change			
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the qualification of its DMOS6 fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.					
<b>Current Fab Site</b>			<b>Additional Fab Site</b>		
<b>Current Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>	<b>New Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>
RFAB	LBC9	300mm	DMOS6	LBC9	300mm
In addition, the datasheet number will be changing:					
<b>Device Family</b>	<b>Change From:</b>		<b>Change To:</b>		
bq28975, bq25971	SLUSCT3A		SLUSCT3C		
 <div style="float: right;">bq25970, bq25971</div>					
SLUSCT3C – NOVEMBER 2017 – REVISED AUGUST 2019					
Changes from Revision B (August 2019) to Revision C					Page
<ul style="list-style-type: none"> <li>Added VBAT Alarm Comparator Accuracy to <a href="#">Electrical Characteristics</a> .....</li> </ul>					11
Changes from Revision A (December 2017) to Revision B					Page
<ul style="list-style-type: none"> <li>Deleted VBAT Alarm Comparator Accuracy from <a href="#">Electrical Characteristics</a> .....</li> </ul>					11
The document is not available on the TI website. Please contact the TI Customer Quality Engineer (CQE) for a copy of the datasheet.					
Qual details are provided in the Qual Data Section.					
<b>Reason for Change:</b>					
Continuity of supply and to accurately reflect device characteristics.					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					

**Changes to product identification resulting from this PCN:****Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
<b>DMOS6</b>	<b>DM6</b>	<b>USA</b>	<b>Dallas</b>

Sample product shipping label (not actual product label)



(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CS0: SHE (21L) CC0: USA  
(22L) AS0: MIA (23L) AC0: MYS

**Product Affected:**

BQ25970YFFR	BQ25970YFFT
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**Qualification Report****Approve Date 19-July-2019****Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: BQ25970YFFR	QBS Device: BQ25910YFFR
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass
ELFR	Early Life Failure Rate, 140C	24 Hours	-	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0
HAST	Unbiased HAST, 130C/85%RH	96 Hours	-	3/231/0
HBM	ESD - HBM	3000 V	1/3/0	3/9/0
CDM	ESD - CDM	1500 V	1/3/0	3/9/0
HTOL	Life Test, 140C	480 Hours	1/77/0	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	3/18/0
TC	Temperature Cycle, -55/125C	700 Cycles	-	3/231/0

- Qual Device BQ25970YFFR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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